



Material Content Data Sheet



Sales Product Name		SPA15N60CFD		Issued		29. August 2013			
MA#		MA000744804							
Package		PG-TO220-3-121		Weight*		2241.73 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	9.195	0.41	0.41	4102	4102	
leadframe	non noble metal	iron	7439-89-6	1.120	0.05		500		
	inorganic material	phosphorus	7723-14-0	0.336	0.02		150		
	non noble metal	copper	7440-50-8	1118.332	49.88	49.95	498870	499520	
wire	non noble metal	aluminium	7429-90-5	2.804	0.13	0.13	1251	1251	
encapsulation	organic material	carbon black	1333-86-4	2.195	0.10		979		
	plastics	epoxy resin	-	206.306	9.20		92030		
	inorganic material	silicondioxide	60676-86-0	888.872	39.65	48.95	396512	489521	
leadfinish	non noble metal	tin	7440-31-5	7.942	0.35	0.35	3543	3543	
plating	non noble metal	nickel	7440-02-0	0.305	0.01		136		
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.01	0	136	
solder	non noble metal	antimony	7440-36-0	0.432	0.02		193		
	noble metal	silver	7440-22-4	1.080	0.05		482		
	non noble metal	tin	7440-31-5	2.807	0.13	0.20	1252	1927	
*deviation	< 10%					Sum in total:	100,00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

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